



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50R500CE		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001581838						
<b>Package</b>		PG-TO252-3-343		<b>Weight*</b>		312.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.939	0.94	0.94	9400	9400
leadframe	non noble metal	iron	7439-89-6	0.137	0.04		439	
	inorganic material	phosphorus	7723-14-0	0.041	0.01		132	
	non noble metal	copper	7440-50-8	137.105	43.86	43.91	438548	439119
wire	non noble metal	aluminium	7429-90-5	4.655	1.49	1.49	14891	14891
encapsulation	organic material	carbon black	1333-86-4	1.281	0.41		4098	
	plastics	epoxy resin	-	24.345	7.79		77871	
	inorganic material	silicondioxide	60676-86-0	102.505	32.79	40.99	327876	409845
leadfinish	non noble metal	tin	7440-31-5	3.834	1.23	1.23	12262	12262
solder	noble metal	silver	7440-22-4	0.069	0.02		220	
	non noble metal	tin	7440-31-5	0.055	0.02		176	
	non noble metal	lead	7439-92-1	2.630	0.84	0.88	8411	8807
heatspreader	non noble metal	iron	7439-89-6	0.033	0.01		106	
	inorganic material	phosphorus	7723-14-0	0.010	0.00		32	
	non noble metal	copper	7440-50-8	32.995	10.55	10.56	105538	105676
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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